

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.40726	100.0	8.58835
			Subtotal	0.40726	100	8.58835
Die	Doped silicon	Silicon (Si)	7440-21-3	0.46472	100.0	9.8
			Subtotal	0.46472	100	9.8
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.04356	10.0	0.91858
	Silver alloy	Silver (Ag)	7440-22-4	0.00871	2.0	0.18372
	Lead alloy	Lead (Pb)	7439-92-1	0.38332	88.0	8.08353
			Subtotal	0.43559	100	9.18583
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01273	100.0	0.26839
			Subtotal	0.01273	100	0.26839
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00697	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00465	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00697	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.02555	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	23.18188	99.81	488.8594
			Subtotal	23.22602	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.24502	100.0	5.167
			Subtotal	0.24502	100	5.167
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	2.25626	3.0	47.58
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.51252	6.0	95.16
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	7.52087	10.0	158.6
	Carbon Black	Carbon black	1333-86-4	0.37604	0.5	7.93
	Filler	Misc. Silica compounds (generic)	14808-60-7	58.66276	78.0	1237.08
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	1.88022	2.5	39.65
			Subtotal	75.20867	100	1586
			Total	100.00001	100	2108.79958

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.